

### **Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

### **Listing of Claims:**

Claims 1-6 (cancelled)

Claim 7 (currently amended): A semiconductor package, comprising:

a substrate;

a die located and supported on said substrate with an adhesive layer between them;

a plurality of signal transferring means which electrically connects said die to said substrate;

a molding compound which seals and protect said die and said plurality of signal transferring means, wherein said molding compound has geometrically a recessed portion located at the top surface of the center part, wherein said die is located right below said recessed portion and fully covered by said molding compound, so that the thickness of said molding compound above said die is less than the thickness on the other portions of said molding compound; and

a heat-spreading device which is attached atop said molding compound to conduct heat from said die to ambient air, wherein said heat-spreading spreading device has a downward bump aligned to said recessed portion, and said molding compound exists between said downward bump and said die, said molding compound and said heat-spreading device being at least partially in surface-to-surface contact with one another;

a thermally conductive adhesive applied between said molding compound and said heat-spreading device; and

a plurality of conductive means attached below said substrate to electrically connect a plurality of conductive traces on said substrate to external circuits.

Claim 8 (original): The semiconductor package of claim 7, wherein said plurality of conductive means includes a plurality of solder balls.

Claim 9 (original): The semiconductor package of claim 7, wherein said plurality of signal transferring means can be a plurality of bonding wires.

Claim 10 (cancelled)

Claim 11 (original): The semiconductor package of claim 7, wherein said heat-spreading device can be made of metal.

Claim 12 (previously presented): The semiconductor package of claim 7, wherein said die has a thermally conductive glue, which conduct heat from said die through said molding compound to said heat-spreading device.

Claims 13-26 (cancelled)

Claim 27 (currently amended): A semiconductor package, at least comprising:

molding means having heat-spreading means contact areas, one of said contact areas being with a recessed portion having a substantially flat surface located at the central part of the top surface, for sealing and protecting a die, which is adhered on a substrate by an adhesive layer and electrically connected to the substrate by a plurality of signal transferring means, wherein said die is located right below said recessed portion and fully covered by said molding means, so that the thickness of said molding means above said die is less than the thickness on the other portions of said molding means; ~~and~~

heat-spreading means for conducting heat from said die to ambient air by attaching atop said molding means, said heat-spreading means having molding means contact areas, one of said molding means contact areas being, ~~wherein said spreading means has a downward bump with a substantially flat surface~~ aligned to said recessed portion, and said molding compound exists between said downward bump and said die;

an adhesive only between said substantially flat surface of said recessed portion of said molding means and said substantially flat surface of said heat-spreading means, the remainder of said heat-spreading means contact areas and said molding means contact areas being in direct contact.

Claim 28 (previously presented): The semiconductor package of claim 27, further comprises a plurality of conductive means attached below said substrate to electrically connect a plurality of conductive traces on said substrate to external circuits.

Claim 29 (previously presented): The semiconductor package of claim 28, wherein said

plurality of conductive means includes a plurality of solder balls.

Claim 30 (previously presented): The semiconductor package of claim 27, wherein said plurality of signal transferring means can be a plurality of bonding wires.

Claim 31 (previously presented): The semiconductor package of claim 27, wherein said heat-spreading means can be made of metal.

Claim 32 (previously presented): The semiconductor package of claim 27, wherein said die has a thermally conductive glue, which conduct heat from said die through said molding means to said heat-spreading device.

**Amendments to the Drawings:**

*Please amend Figures 1 and 2 of the application as indicated in the attached sheets (enclosed in duplicate).*